## **AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions and listings of claims in the application:

## **LISTING OF CLAIMS:**

1. (currently amended): A method of forming a carbon layer by vapor phase deposition, comprising the steps of:

adjusting a content of particles having a particle size of 0.5  $\mu m$  or more in a film deposition system of the carbon layer to 1000 particles/ft<sup>3</sup>/min or less; and then

starting a film deposition process of the carbon layer;

wherein said carbon layer is formed as a protective coating on a thermal head performing thermal recording;

wherein the carbon layer is formed directly on top of a lower protective layer such that the thermal head has a protective coating, and

wherein the carbon layer and the lower protective layer are successively formed on the thermal head under a continuous vacuum.

- 2. (original): The method according to claim 1, wherein said content of the particles having the particle size of 0.5  $\mu$ m or more is reduced to 500 particles/ft<sup>3</sup>/min.
  - 3. (cancelled)
  - 4. (original): The method according to claim 1, wherein a lower limit of said content of

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the particles having the particle size of 0.5  $\mu$ m or more ranges between 50 particles/ft<sup>3</sup>/min and 100 particles/ft<sup>3</sup>/min.

- 5. (currently amended): The method of forming a carbon layer by vapor phase deposition according to claim  $\underline{1}$  3, wherein said carbon layer is formed on top of an intermediate layer and the intermediate layer is formed on top of a lower protective layer such that the thermal head has a protective coating of a three-layer structure.
- 6. (previously presented): The method of forming a carbon layer by vapor phase deposition according to claim 5, wherein said carbon layer has a thickness from 0.5  $\mu$ m to 5  $\mu$ m, said intermediate layer has a thickness from 0.05  $\mu$ m to 1  $\mu$ m, and said lower protective layer has a thickness from 0.2  $\mu$ m to 20  $\mu$ m.
  - 7. (canceled).
  - 8. (cancelled)
- 9. (previously presented): The method according to claim 1, wherein said step of adjusting the content of particles includes cleaning an interior of a chamber of the film deposition system in which the film deposition process occurs using a dust cloth that produces no more than 3000 particles/cfm.

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10. (previously presented): The method according to claim 1, wherein said step of adjusting the content of particles includes cleaning an interior of a chamber of the film deposition system in which the film deposition process occurs using a dust cloth that produces no more than 1000 particles/cfm.

- 11. (previously presented): The method according to claim 1, wherein said step of adjusting the content of particles includes cleaning an interior of a chamber of the film deposition system in which the film deposition process occurs using a dust cloth that produces no more than 300 particles/cfm.
- 12. (previously presented): The method according to claim 9, wherein said step of adjusting the content of particles further includes pumping out the chamber after cleaning to remove floating particles within the chamber.
- 13. (new): A method of forming a carbon layer by vapor phase deposition, comprising the steps of:

adjusting a content of particles having a particle size of 0.5  $\mu$ m or more in a film deposition system of the carbon layer to 1000 particles/ft<sup>3</sup>/min or less; and then

starting a film deposition process of the carbon layer;

wherein said carbon layer is formed as a protective coating on a thermal head performing thermal recording,

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wherein said carbon layer is formed on top of an intermediate layer and the intermediate layer is formed on top of a lower protective layer such that the thermal head has a protective

coating of a three-layer structure, and

wherein the carbon layer, the intermediate layer, and the lower protective layer are

successively formed on the thermal head under a continuous vacuum.

14. (new): The method according to claim 13, wherein said content of the particles

having the particle size of 0.5 µm or more is reduced to 500 particles/ft<sup>3</sup>/min.

15. (new): The method according to claim 13, wherein a lower limit of said content of the

particles having the particle size of 0.5 µm or more ranges between 50 particles/ft<sup>3</sup>/min and 100

particles/ft<sup>3</sup>/min.

16. (new): The method according to claim 13, wherein said carbon layer has a thickness

from 0.5  $\mu m$  to 5 $\mu m$ , said intermediate layer has a thickness from 0.05  $\mu m$  to 1  $\mu m$ , and said

lower protective layer has a thickness from 0.2 µm to 20 µm.

17. (new): The method according to claim 13, wherein said step of adjusting the content

of particles includes cleaning an interior of a chamber of the film deposition system in which the

film deposition process occurs using a dust cloth that produces no more than 3000 particles/cfm.

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18. (new): The method according to claim 13, wherein said step of adjusting the content

of particles includes cleaning an interior of a chamber of the film deposition system in which the

film deposition process occurs using a dust cloth that produces no more than 1000 particles/cfm.

19. (new): The method according to claim 13, wherein said step of adjusting the content

of particles includes cleaning an interior of a chamber of the film deposition system in which the

film deposition process occurs using a dust cloth that produces no more than 300 particles/cfm.

20. (new): The method according to claim 17, wherein said step of adjusting the content

of particles further includes pumping out the chamber after cleaning to remove floating particles

within the chamber.